

1 1. At least one packaged integrated circuit
2 comprising:
3 a semiconductor die;
4 a flexible substrate, said die attached to said
5 substrate; and
6 at least two buildup layers formed over said
7 substrate, a cavity formed in said buildup layers, and said
8 die mounted in said cavity.

1 2. The circuit of claim 1 including lands below said
2 flexible substrate, said lands coupled to solder balls.

1 3. The circuit of claim 1 wherein said flexible
2 substrate is formed of polyamide.

1 4. The circuit of claim 1 wherein said cavity is
2 stepped.

1 5. The circuit of claim 4 including an
2 interconnection layer between said buildup layers.

1 6. The circuit of claim 5 including an
2 interconnection layer between one of said buildup layers
3 and said flexible substrate.

1 7. The circuit of claim 6 including wire bonds from
2 one of said interconnection layers to said die.

1 8. The circuit of claim 7 including a die attach
2 between said cavity and said die.

1 9. The circuit of claim 1 wherein the upper surface
2 of the upper buildup layer is higher than the upper surface
3 of said die.

1 10. The circuit of claim 1 including a folded
2 package.

1 11. A method comprising:
2 securing a semiconductor die within a cavity in a
3 flexible package.

1 12. The method of claim 11 including securing said
2 die in a stepped cavity.

1 13. The method of claim 11 including securing said
2 die in a cavity formed by at least two buildup layers.

1 14. The method of claim 13 including providing
2 interconnection layers between said buildup layers.

1 15. The method of claim 14 including providing an
2 interconnection layer between a buildup layer and a
3 flexible substrate.

1 16. The method of claim 11 including packaging said
2 die at a level in said cavity below the upper surface of
3 said cavity.

1 17. The method of claim 16 including wire bonding
2 from said package to said die.

1 18. The method of claim 11 including forming a
2 flexible substrate of polyamide in said package.

1 19. The method of claim 11 including forming a folded
2 package.

1 20. A package comprising:
2 a flexible substrate; and
3 a layer over said substrate, said layer having a
4 cavity formed therein to receive a die.

1 21. The package of claim 20 wherein said layer is
2 formed of at least two buildup layers.

1 22. The package of claim 21 wherein said cavity is
2 stepped.

1 23. The package of claim 20 including solder balls
2 coupled thereto.

1 24. The package of claim 20 wherein said flexible
2 substrate includes polyamide.

1 25. The package of claim 21 including an
2 interconnection layer between said buildup layers.

1 26. The package of claim 25 including a pair of
2 buildup layers over said flexible substrate.

1 27. The package of claim 25 including an
2 interconnection layer between said substrate and one of
3 said buildup layers.

1 28. The package of claim 20 including a die attach in
2 said cavity.

1 29. The package of claim 20 wherein said package is a
2 folded package.